ELECTRONIC MATERIALS
CMP TECHNOLOGIES

ACE NANOCHEM

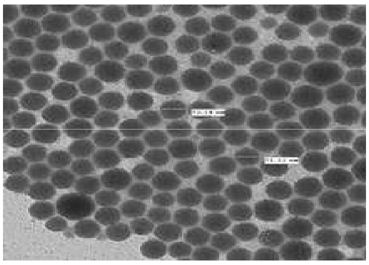
ACESOL® - series
Colloidal Silica
Oxide CMP Slurry

ACESOL®2580,2012 (Dilution System Slurry)

DESCRIPTION

Acesol® slurries offer a complete solution for your polishing requirements based on the latest colloidal silica technology showing exceptional stability and high manufacturing reproducibility

TEM Image



Precisely Controlled
ACESOL® Particles.

SPECIFICATION

Abrasive	**Colloidal Silica**
Mean Particle	**70-120 nm**
Specific Gravity (25℃)	**1.16+/-0.005**
Percent Silica (wt%)	**25.0+/-0.5**
Viscosity (25℃)	**<5**
pH	**10.5~ 11.5**
Shelf life	**More than 12 months**

Polishing Condition (8” Fab)

Polisher : AMAT Mirra-Mesa	**Auriga**
Pad : Perforated IC1400/ Suba IV	**IC1000**
Speed : TEOS 93/87	**TEOS 20/8**
Slurry Flow Rate : 160 ml/min	**750 ml/min**
Press(TEOS) : 3.2/6.1/3.2	**430lbs**

Typical Process Results 2580

Oxide	**Polishing Tool**	**ACESOL2580**
R/R(aver.Å)	Auriga	**TEOS 3300** Å/min **BPSG 3600** Å/min
	Mirra-mesa	**TEOS 3000** Å/min **BPSG 3300** Å/min
Within Uniformity(%)		**< 5**

Typical Process Results 2012

Oxide	**Polishing Tool**	**ACESOL2012**
R/R(aver)	Auriga	**TEOS 3300** Å/min **BPSG 3200** Å/min
	Mirra-mesa	**TEOS 2500** Å/min **HDP 2200** Å/min **P-SiN 600** Å/min
Within Uniformity(%)		**< 5**

Can be dilution before use by half with DI water.

ACENANOCHEM CO., LTD.